

a plurality of conduction sections formed on the second surface, each conduction section defining at least part of an external terminal, the conduction sections being electrically connected to the leads via the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and the through-holes are arranged corresponding to the respective leads such that the substrate main body that is cut along predetermined through-holes allows remaining through-holes connected to the respective leads to define the conduction sections.

3. (Twice Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections are electrically connected to the leads through the through-holes.

4. (Twice Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body has the plurality of through-holes for each of the leads, and the conduction sections are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

7. (Four Times Amended) A semiconductor apparatus, comprising:

- a semiconductor device having a plurality of electrodes;
- a substrate main body having a first surface for mounting the semiconductor device, a second surface and a plurality of through-holes;
- a plurality of leads formed on the first surface, the plurality of leads extending from a peripheral area toward a central area of the substrate main body; and
- a plurality of conduction sections formed on the second surface, one of the conduction sections defining an external terminal, the conduction sections being electrically connected to the leads through the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and the through-holes are arranged

corresponding to the respective leads such that the substrate main body that is cut along predetermined through-holes allows remaining through-holes of the respective leads to define the conduction sections.

9. (Amended) The semiconductor apparatus of claim 7, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections are electrically connected the leads through the through-holes.

10. (Amended) The semiconductor apparatus of claim 7, wherein the substrate main body has the plurality of through-holes for each of the leads, and the conduction sections are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

REMARKS

Claims 1, 3-4, 6-7 and 9-12 are pending in this application. By this Amendment, claims 1, 3, 4, 7, 9 and 10 are amended.

The attached Appendix includes a marked-up copy of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Entry of the amendments is proper under 37 CFR §1.116 since the amendments: (a) place the application in condition for allowance (for the reasons discussed herein); (b) do not raise any new issue requiring further search and/or consideration (since the amendments amplify issues previously discussed throughout prosecution); (c) satisfy a requirement of form asserted in the previous Office Action; (d) do not present any additional claims without canceling a corresponding number of finally rejected claims; and (e) place the application in better form for appeal, should an appeal be necessary. The amendments are necessary and were not earlier presented because they are made in response to arguments raised in the final rejection. Entry of the amendments is thus respectfully requested.